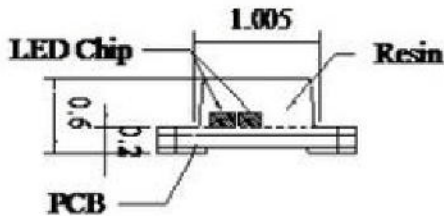
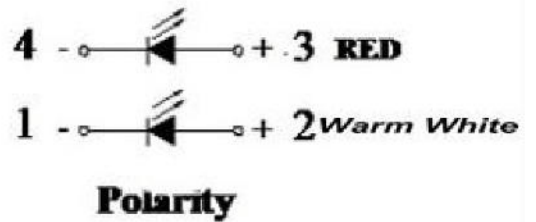
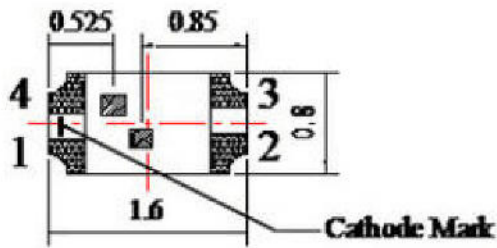


fischer-modell

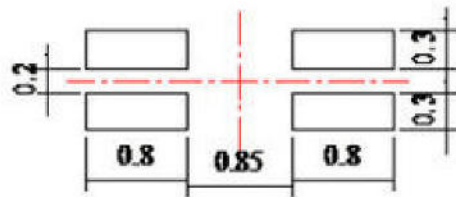
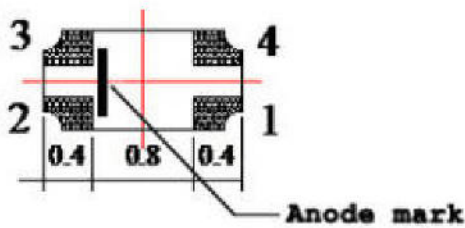
0.60mm Height 0603 Package
Bi-color (Multi-color) Chip LED
Technical Data Sheet

Part No.: **20006505**

◆ Package Dimension:



Recommended Soldering Pad Dimensions



Unit: mm
Tolerance: ±0.10mm

Part No.	Chip Material		Lens Color	Source Color
	R	AlGaInP	Yellow Diffused	Hyper Red
	W	InGaN		Warm White

Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.10mm (.004") unless otherwise specified.
3. Specifications are subject to change without notice.

◆ Absolute Maximum Ratings at Ta=25°C

Parameters	Symbol	Emitting Color	Max.	Unit
Power Dissipation	PD	Hyper Red	65	mW
		Warm White	85	
Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width)	IFP	Hyper Red	100	mA
		Warm White	100	
Continuous Forward Current	IF	Hyper Red	25	mA
		Warm White	30	
Reverse Voltage	VR	5		V
Electrostatic Discharge (HBM)	ESD	2000		V
Operating Temperature Range	Topr	-40°C to +80°C		
Storage Temperature Range	Tstg	-40°C to +85°C		
Soldering Temperature	Tsld	260°C for 5 Seconds		

◆ Electrical Optical Characteristics at Ta=25°C

Parameters	Symb ol	Emitting Color	Min.	Typ.	Max.	Unit	Test Condition
Luminous Intensity	IV	Hyper Red	80	150	---	mcd	IF=20mA (Note 1)
		Warm White	250	400	---		
Viewing Angle	2θ _{1/2}	Hyper Red	---	120	---	Deg	IF=20mA (Note 2)
		Warm White	---	120	---		
Peak Emission Wavelength	λ _p	Hyper Red	---	620	---	nm	IF=20mA
Chromaticity Coordinates	X	Warm White	0.46		0.50		
	Y		0.42		0.46		
Forward Voltage	VF	Hyper Red	2.80	2.90	3.00	V	IF=20mA
		Warm White	1.80	2.00	2.10		
Reverse Current	IR	Hyper Red	---	---	10	μA	V _R =5V
		Warm White					

Notes:

1. Luminous Intensity Measurement allowance is ± 10%.
2. θ_{1/2} is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
3. The dominant wavelength (λ_d) is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.